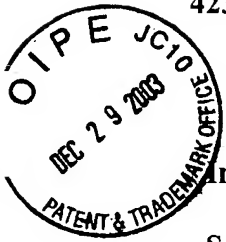


42390.P12897

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Dias, et al.

Serial No.: 10/000,229

Filed: November 30, 2001

For: Backside Metallization On Sides Of
Microelectronic Dice For Effect
Thermal Contact With Heat
Dissipation Devices

Examiner: Hoai V. Pham

Group Art Unit: 2814


Attorney Docket No.: 42390P12897

Confirmation No.: 9231

CERTIFICATE OF MAILING

I hereby certify that this paper or fee along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner of Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

12/22/03
Date of Deposit


Signature of registered practitioner or other person having reasonable basis to expect mailing to occur on date of deposit shown pursuant to 37 C.F.R. § 1.8(a)(1)(ii)

DEBORAH L. HIGHAM
Typed/printed name of person whose signature is contained above

RECEIVED
JAN - 5 2004
TECHNOLOGY CENTER 2800

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the September 24, 2003 Office Action, please consider the following amendments and remarks.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begin on page 3 of this paper.

Remarks/Arguments begin on page 11 of this paper